

REMARKS

Claims 1-51 are all the claims pending in the Application. Claims 1-14, 20-26 and 28-45 are withdrawn from further consideration pursuant to 37 C.F.R. § 1.142(b) as being drawn to a nonelected groups, further to the Response to Election filed on August 20, 2007, there being no allowable generic or linking claim to the whole claimed invention.

Claims 15-19, 27, and 46-51 are all the claims that have been examined.

Claim Rejections - 35 U.S.C. § 112

Claims 46, 48 and 50 are rejected under 35 U.S.C. § 112, first paragraph, as allegedly failing to comply with the written description requirement. The Examiner asserts that the term “identical number of substantially solid layers” is not defined in the specification.

Claims 46, 48 and 50 are also rejected under 35 U.S.C. § 112, second paragraph, as allegedly indefinite for failing to particularly point out and distinctly claim the subject matter which applicants regard as the invention.

By this Amendment, Applicants amend claims 46, 48, and 50 to more clearly define their features, and request that the rejections of these claims be withdrawn.

Claim Rejections - 35 U.S.C. § 102

Claims 15-18, 27 and 46-51 are rejected under 35 U.S.C. § 102(b) as allegedly anticipated by Sakamoto et al. (US Patent 6,281,446, hereinafter “Sakamoto”).

Applicants submit that Sakamoto focuses on the different densities of the boards and the insertion of the carrier board into a cavity in the motherboard. It does not focus on minimizing

waste or maximizing flexibility in designing a multi-layered wiring board, as the present invention does. Sakamoto also specifies that the carrier board is attached to the mother board via solder, gold bumps, or conductive paste. See col. 4, line 26-32. Significantly, the present application requires “laminating”, which is not disclosed in Sakamoto.

In response to the arguments presented in the Amendment dated January 15, 2008, the Examiner asserts that the term “laminating” is construed as merely bonding together different layers, and that Sakamoto teaches bonding such different layers (see Office Action, page 5, section 10).

Applicants submit that the Examiner improperly interprets the term “laminating”. Even if the plain meaning of the term is as the Examiner asserts, the Examiner must defer to the definitions of terms given in the specification¹. As clearly discussed in the specification at page 30, lines 6-17, laminating includes positioning the members, then superposing, heating, and pressing the members with a vacuum pressing machine. In contrast, Sakamoto only discloses “a carrier board arranged within [a] cavity and electrically connected to [a] mother board.” See Sakamoto claim 1, col. 10, line 46-57.

By this Amendment, Applicants amend claims 15, 16, and 27 in order to clarify the appropriate definition of “laminating”. Applicants submit that as amended, claims 15, 16, and 27 are patentable over the cited art, and request that the rejection be withdrawn. Applicants further

¹ MPEP 2111.01(I), page 2100-38

submit that claims 17 and 46-51 are patentable at least by virtue of their respective dependencies from claims 15, 16, or 27.

Claim Rejections - 35 U.S.C. § 103

Claim 19 is rejected under 35 U.S.C. § 103(a) as allegedly unpatentable over Sakamoto.

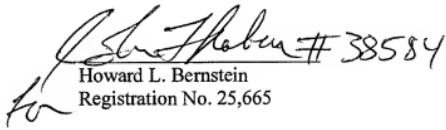
As Sakamoto does not render the features of the independent claims obvious, Applicants submit that claim 19 is patentable at least by virtue of its dependency from independent claims 15 and 16.

Conclusion

In view of the above, reconsideration and allowance of this application are now believed to be in order, and such actions are hereby solicited. If any points remain in issue which the Examiner feels may be best resolved through a personal or telephone interview, the Examiner is kindly requested to contact the undersigned at the telephone number listed below.

The USPTO is directed and authorized to charge all required fees, except for the Issue Fee and the Publication Fee, to Deposit Account No. 19-4880. Please also credit any overpayments to said Deposit Account.

Respectfully submitted,



Howard L. Bernstein
Registration No. 25,665

SUGHRUE MION, PLLC
Telephone: (202) 293-7060
Facsimile: (202) 293-7860

WASHINGTON OFFICE
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CUSTOMER NUMBER

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